

(57) Abstract: The present application discloses a hybrid package chip and an optical transmitter, the hybrid package chip comprises: a first sub-chip, which comprises at least one first waveguide and at least one first electrode; and a second sub-chip, which comprises at least one second waveguide and at least one second electrode. The first waveguide is optically coupled to the corresponding second waveguide; a first electrode of the first sub-chip and a corresponding second electrode of the second sub-chip are electrically connected to one another by means of a first conductive structure, so as to receive a modulated electrical signal; and in a working state, the first sub-chip receives external input light and outputs the light by means of the first waveguide, the at least one first electrode modulates the input light so as to output modulated light, and the second waveguide receives a portion of light coupled from the first sub-chip. By using a non-bonding means, the present application improves the means by which a silicon photonic sub-chip and a thin-film lithium niobate based optoelectronic sub-chip are integrated, and reduces the difficulty of coupling between a lithium niobate waveguide and a silicon optical waveguide while reducing the difficulty of the process.